



### PRODUCT DESCRIPTION

Laird Tflex™ HD80000 is the latest product in the High Deflection gap filler series. Tflex™ HD80000 combines 6 W/mK thermal conductivity with superior pressure versus deflection characteristics. The combination will allow minimal stress on components while also yielding low thermal resistance. As a result, less mechanical and thermal stresses will be experienced within your device.

The Tflex HD80000 material is extremely soft, but also can be handled and applied manually without the need to add a fiberglass or other reinforcement layer, maintaining the superior thermal performance of the product.

### FEATURES AND BENEFITS

- 6 W/mK thermal conductivity
- Low pressure versus deflection
- Excellent surface wetting for low contact resistance
- No fiberglass reinforcement
- Minimizes board and component stress
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

### SPECIFICATIONS

| TYPICAL PROPERTIES          | VALUE                         | TEST METHOD           |
|-----------------------------|-------------------------------|-----------------------|
| Construction & Composition  | Ceramic filled silicone sheet | N/A                   |
| Color                       | Teal                          | Visual                |
| Thickness Range             | 1 mm (0.040") - 5.0mm (0.20") | N/A                   |
| Thickness Tolerance         | +/- 10%                       | N/A                   |
| Thermal Conductivity (W/mK) | 6.0                           | Hot Disk              |
| Density (g/cc)              | 3.3                           | Helium Pycnometer     |
| Hardness (Shore 00, 3 sec)  | 40                            | ASTM D2240            |
| Hardness (Shore 00, 30 sec) | 32                            | ASTM D2240            |
| Outgassing TML (weight %)   | 0.3                           | ASTM E595             |
| Outgassing CVCM (weight %)  | 0.04                          | ASTM E595             |
| Temperature Range           | -40°C to 150°C                | Laird Test Method     |
| Rth@ 50 mils, 10 psi        | 0.330                         | ASTM D5470 (Modified) |
| Dielectric Constant @ 1 MHz | 9                             | ASTM D150             |
| UL Flammability Rating      | V-0                           | UL 94                 |
| Volume Resistivity          | 1.06 x 10 <sup>16</sup>       | ASTM D257             |

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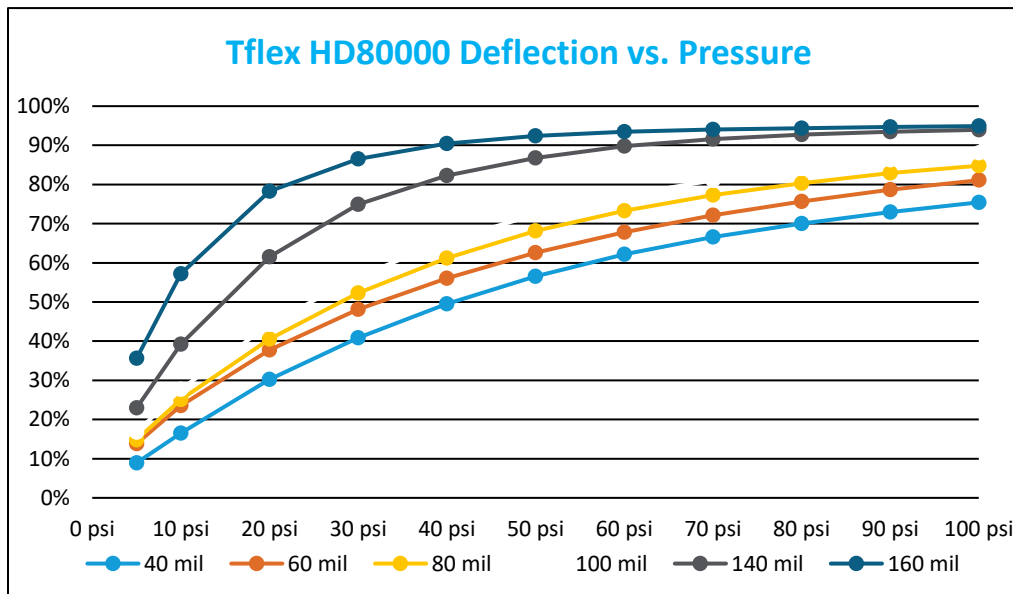
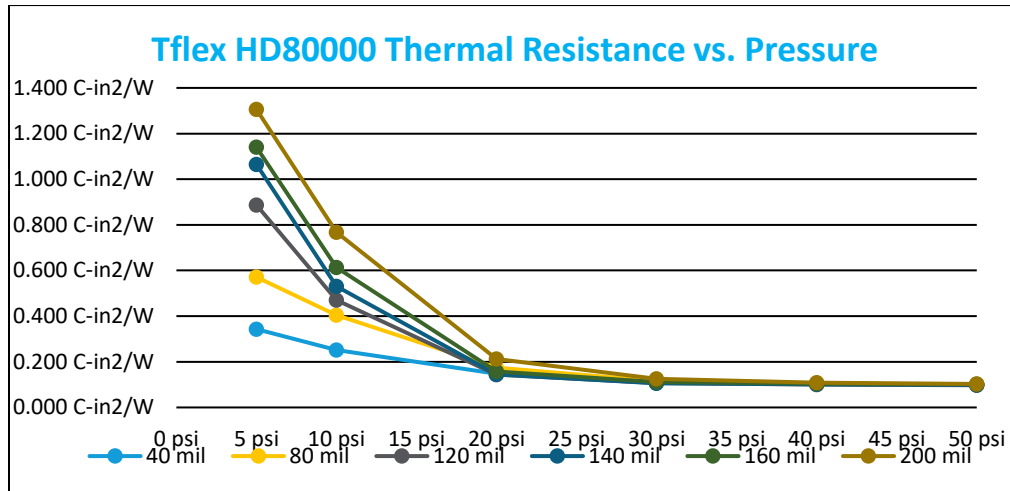
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## AVAILABILITY

### STANDARD THICKNESSES

- 1.0 mm (0.040") to 5.0 mm (0.200") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 9" x 9" or custom die cut parts

## PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. HD8xxxx indicates Tflex HD80000 product line with thickness in microns

### EXAMPLES:

- Tflex™ HD81000 = 1000 microns / 0.040" thick Tflex™ HD80000 material

## Данный компонент на территории Российской Федерации

**Вы можете приобрести в компании MosChip.**

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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